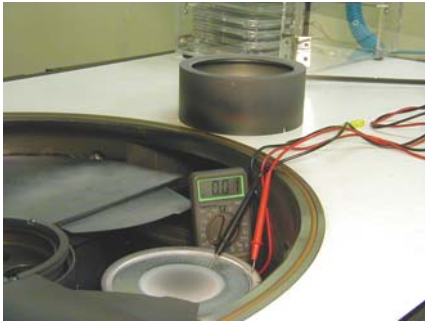


# OPERATING PROCEDURE CVC 601 DC Sputter Deposition Changing 6-Inch Target

Rev. 11/29/2001

## Follow Operating Procedures for Venting.

1. Remove two inserts from Rotostrate platen.
2. Use the two openings for hand holds. Lift platen and set aside.
3. Loosen three screws located on side of cathode shield.
4. Lift off the cathode shield and set it aside.
5. Remove four screws in the target ring. Remove the target ring.
6. Lift out target and place in case. Store target in dry box.
7. Place desired material target on cathode.
6. Position target ring on target, then insert and tighten the four screws.
7. With the ohmmeter to a high resistance scale setting, check the resistance of target to ring. It should read a closed circuit (nearly 0)



8. Reset the cathode shield and tighten the three screws.
9. With the ohmmeter, check the resistance of the target to the cathode shield. It should read an open circuit (off scale).
10. Replace platen and check turning of rotostrate.
11. Change material cards in front panel.

## Return to Operating Procedures for Loading substrates.

